

MITSUBISHI HVIGBT MODULES  
**CM2400HCB-34N**

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

HIGH POWER SWITCHING USE  
 INSULATED TYPE

**CM2400HCB-34N**



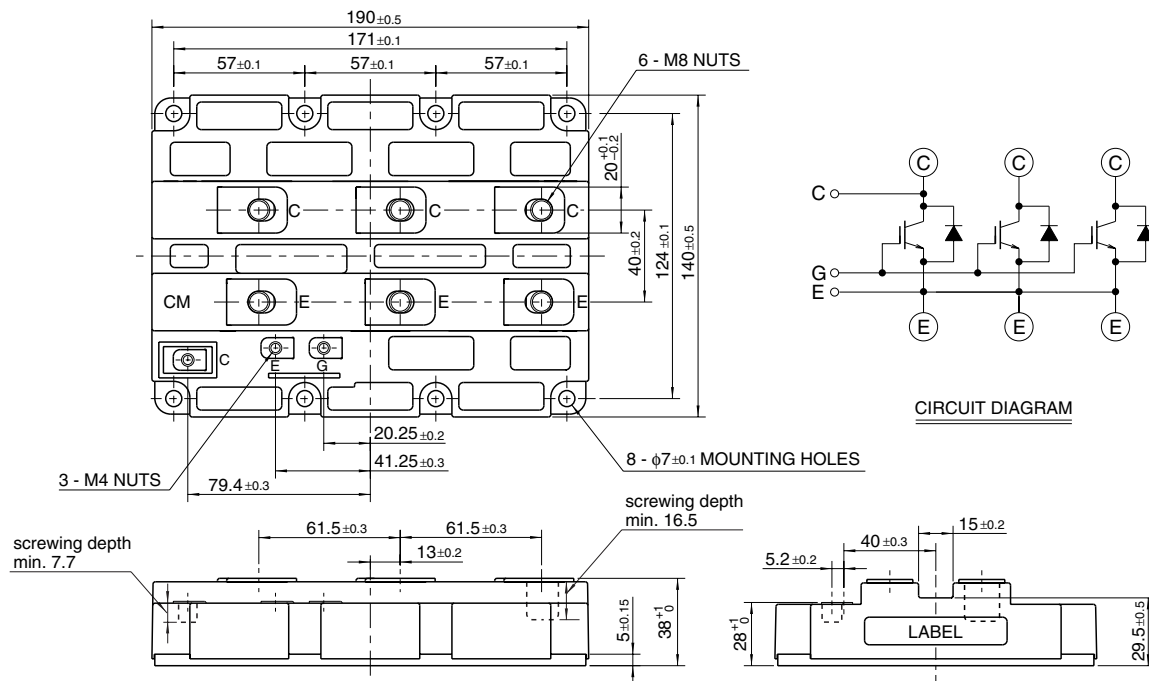
- IC ..... 2400 A
- VCES ..... 1700 V
- Insulated Type
- 1-element in a Pack
- AISiC Baseplate
- Trench Gate IGBT : CSTBT™
- Soft Reverse Recovery Diode

**APPLICATION**

Traction drives, High Reliability Converters / Inverters, DC choppers

**OUTLINE DRAWING & CIRCUIT DIAGRAM**

Dimensions in mm



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Sep. 2009

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## MAXIMUM RATINGS

| Symbol           | Item                               | Conditions                                                                                                  | Ratings    | Unit |
|------------------|------------------------------------|-------------------------------------------------------------------------------------------------------------|------------|------|
| V <sub>CES</sub> | Collector-emitter voltage          | V <sub>GE</sub> = 0V, T <sub>J</sub> = 25°C                                                                 | 1700       | V    |
| V <sub>GES</sub> | Gate-emitter voltage               | V <sub>CE</sub> = 0V, T <sub>J</sub> = 25°C                                                                 | ± 20       | V    |
| I <sub>C</sub>   | Collector current                  | DC, T <sub>c</sub> = 80°C                                                                                   | 2400       | A    |
| I <sub>CM</sub>  |                                    | Pulse (Note 1)                                                                                              | 4800       | A    |
| I <sub>E</sub>   | Emitter current (Note 2)           | DC                                                                                                          | 2400       | A    |
| I <sub>EM</sub>  |                                    | Pulse (Note 1)                                                                                              | 4800       | A    |
| P <sub>c</sub>   | Maximum power dissipation (Note 3) | T <sub>c</sub> = 25°C, IGBT part                                                                            | 15600      | W    |
| V <sub>iso</sub> | Isolation voltage                  | RMS, sinusoidal, f = 60Hz, t = 1 min.                                                                       | 4000       | V    |
| T <sub>J</sub>   | Junction temperature               |                                                                                                             | −40 ~ +150 | °C   |
| T <sub>op</sub>  | Operating temperature              |                                                                                                             | −40 ~ +125 | °C   |
| T <sub>stg</sub> | Storage temperature                |                                                                                                             | −40 ~ +125 | °C   |
| t <sub>psc</sub> | Maximum short circuit pulse width  | V <sub>CC</sub> = 1000V, V <sub>CE</sub> ≤ V <sub>CES</sub> , V <sub>GE</sub> = 15V, T <sub>J</sub> = 125°C | 10         | μs   |

## ELECTRICAL CHARACTERISTICS

| Symbol                | Item                                       | Conditions                                                                                                                                                                 | Limits |              |           | Unit |
|-----------------------|--------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------|--------------|-----------|------|
|                       |                                            |                                                                                                                                                                            | Min    | Typ          | Max       |      |
| I <sub>CES</sub>      | Collector cutoff current                   | V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V<br>T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C                                                               | —      | —            | 9<br>18   | mA   |
| V <sub>GE(th)</sub>   | Gate-emitter threshold voltage             | V <sub>CE</sub> = 10 V, I <sub>C</sub> = 240 mA, T <sub>J</sub> = 25°C                                                                                                     | 5.5    | 6.5          | 7.5       | V    |
| I <sub>GES</sub>      | Gate leakage current                       | V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V, T <sub>J</sub> = 25°C                                                                                           | —      | —            | 0.5       | μA   |
| C <sub>ies</sub>      | Input capacitance                          | V <sub>CE</sub> = 10 V, V <sub>GE</sub> = 0 V, f = 100 kHz, T <sub>J</sub> = 25°C                                                                                          | —      | 396          | —         | nF   |
| C <sub>oes</sub>      | Output capacitance                         |                                                                                                                                                                            | —      | 21.6         | —         | nF   |
| C <sub>res</sub>      | Reverse transfer capacitance               |                                                                                                                                                                            | —      | 6.3          | —         | nF   |
| Q <sub>g</sub>        | Total gate charge                          | V <sub>CC</sub> = 900 V, I <sub>C</sub> = 2400 A, V <sub>GE</sub> = ±15 V, T <sub>J</sub> = 25°C                                                                           | —      | 27.4         | —         | μC   |
| V <sub>CE(sat)</sub>  | Collector-emitter saturation voltage       | I <sub>C</sub> = 2400 A (Note 4)<br>V <sub>GE</sub> = 15 V<br>T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C                                                              | —      | 2.10<br>2.35 | 2.70<br>— | V    |
| t <sub>d(on)</sub>    | Turn-on delay time                         | V <sub>CC</sub> = 900 V, I <sub>C</sub> = 2400 A, V <sub>GE</sub> = ±15 V<br>R <sub>G(on)</sub> = 0.8 Ω, T <sub>J</sub> = 125°C, L <sub>s</sub> = 80 nH<br>Inductive load  | —      | —            | 1.50      | μs   |
| t <sub>r</sub>        | Turn-on rise time                          |                                                                                                                                                                            | —      | —            | 0.60      | μs   |
| E <sub>on(10%)</sub>  | Turn-on switching energy (Note 5)          |                                                                                                                                                                            | —      | 0.65         | —         | J/P  |
| t <sub>d(off)</sub>   | Turn-off delay time                        | V <sub>CC</sub> = 900 V, I <sub>C</sub> = 2400 A, V <sub>GE</sub> = ±15 V<br>R <sub>G(off)</sub> = 1.1 Ω, T <sub>J</sub> = 125°C, L <sub>s</sub> = 80 nH<br>Inductive load | —      | —            | 3.00      | μs   |
| t <sub>f</sub>        | Turn-off fall time                         |                                                                                                                                                                            | —      | —            | 0.60      | μs   |
| E <sub>off(10%)</sub> | Turn-off switching energy (Note 5)         |                                                                                                                                                                            | —      | 0.70         | —         | J/P  |
| V <sub>EC</sub>       | Emitter-collector voltage (Note 2)         | I <sub>E</sub> = 2400 A (Note 4)<br>V <sub>GE</sub> = 0 V<br>T <sub>J</sub> = 25°C<br>T <sub>J</sub> = 125°C                                                               | —      | 2.20<br>1.85 | 3.00<br>— | V    |
| t <sub>rr</sub>       | Reverse recovery time (Note 2)             | V <sub>CC</sub> = 900 V, I <sub>E</sub> = 2400 A, V <sub>GE</sub> = ±15 V<br>R <sub>G(on)</sub> = 0.8 Ω, T <sub>J</sub> = 125°C, L <sub>s</sub> = 80 nH<br>Inductive load  | —      | —            | 1.50      | μs   |
| Q <sub>rr</sub>       | Reverse recovery charge (Note 2)           |                                                                                                                                                                            | —      | 750          | —         | μC   |
| E <sub>rec(10%)</sub> | Reverse recovery energy (Note 2), (Note 5) |                                                                                                                                                                            | —      | 0.50         | —         | J/P  |

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4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

## THERMAL CHARACTERISTICS

| Symbol         | Item                       | Conditions                                                                                  | Limits |     |      | Unit |
|----------------|----------------------------|---------------------------------------------------------------------------------------------|--------|-----|------|------|
|                |                            |                                                                                             | Min    | Typ | Max  |      |
| $R_{th(j-c)Q}$ | Thermal resistance         | Junction to Case, IGBT part                                                                 | —      | —   | 8.0  | K/kW |
| $R_{th(j-c)R}$ | Thermal resistance         | Junction to Case, FWDi part                                                                 | —      | —   | 12.0 | K/kW |
| $R_{th(c-f)}$  | Contact thermal resistance | Case to Fin, $\lambda_{grease} = 1\text{W/m}\cdot\text{K}$ , $D_{(c-f)} = 100\ \mu\text{m}$ | —      | 6.0 | —    | K/kW |

## MECHANICAL CHARACTERISTICS

| Symbol        | Item                       | Conditions                    | Limits |      |      | Unit |
|---------------|----------------------------|-------------------------------|--------|------|------|------|
|               |                            |                               | Min    | Typ  | Max  |      |
| $M_t$         | Mounting torque            | M8: Main terminals screw      | 7.0    | —    | 13.0 | N·m  |
| $M_s$         |                            | M6: Mounting screw            | 3.0    | —    | 6.0  | N·m  |
| $M_t$         |                            | M4: Auxiliary terminals screw | 1.0    | —    | 2.0  | N·m  |
| m             | Mass                       |                               | —      | 1.5  | —    | kg   |
| CTI           | Comparative tracking index |                               | 600    | —    | —    | —    |
| $d_a$         | Clearance                  |                               | 19.5   | —    | —    | mm   |
| $d_s$         | Creepage distance          |                               | 32.0   | —    | —    | mm   |
| $L_{P\ CE}$   | Parasitic stray inductance |                               | —      | 10   | —    | nH   |
| $R_{CC'+EE'}$ | Internal lead resistance   | $T_c = 25^\circ\text{C}$      | —      | 0.18 | —    | mΩ   |

- Note 1. Pulse width and repetition rate should be such that junction temperature ( $T_j$ ) does not exceed  $T_{opmax}$  rating ( $125^\circ\text{C}$ ).  
 2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).  
 3. Junction temperature ( $T_j$ ) should not exceed  $T_{jmax}$  rating ( $150^\circ\text{C}$ ).  
 4. Pulse width and repetition rate should be such as to cause negligible temperature rise.  
 5.  $E_{on(10\%)} / E_{off(10\%)} / E_{rec(10\%)}$  are the integral of  $0.1V_{CE} \times 0.1I_C \times dt$ .

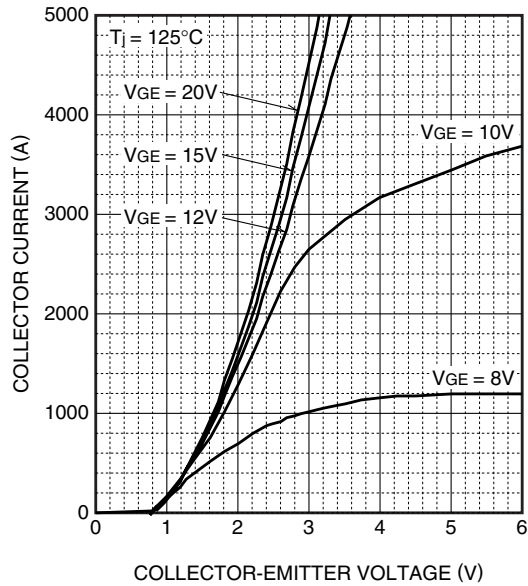
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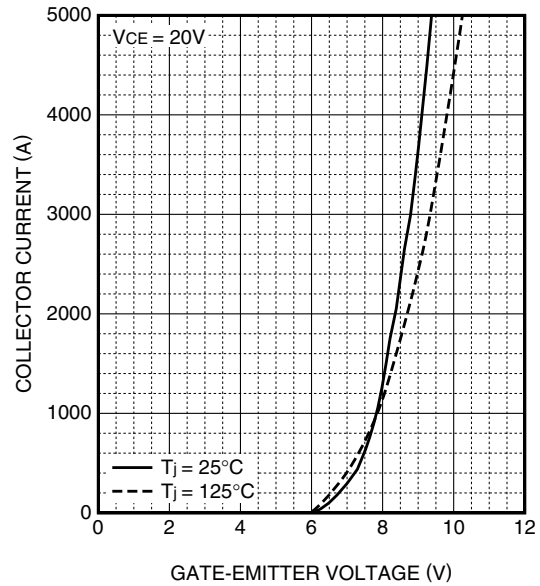
4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

## PERFORMANCE CURVES

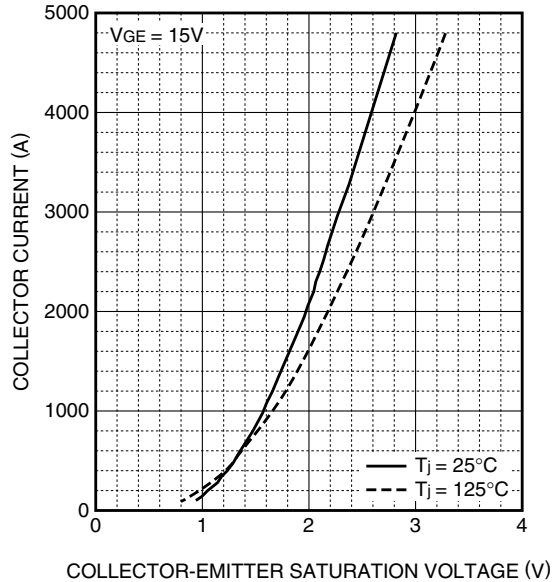
OUTPUT CHARACTERISTICS  
(TYPICAL)



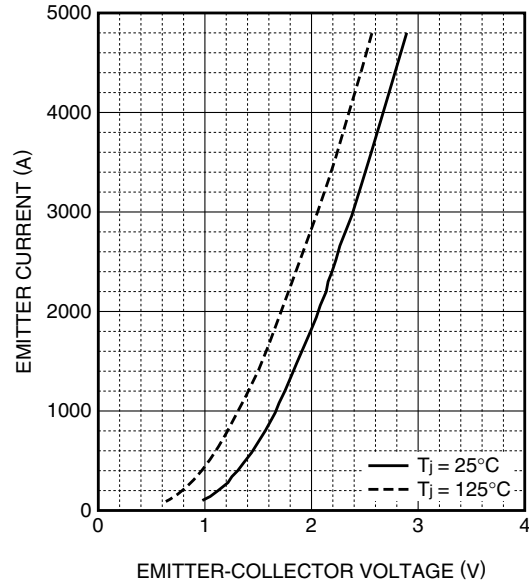
TRANSFER CHARACTERISTICS  
(TYPICAL)



COLLECTOR-EMITTER SATURATION  
VOLTAGE CHARACTERISTICS  
(TYPICAL)



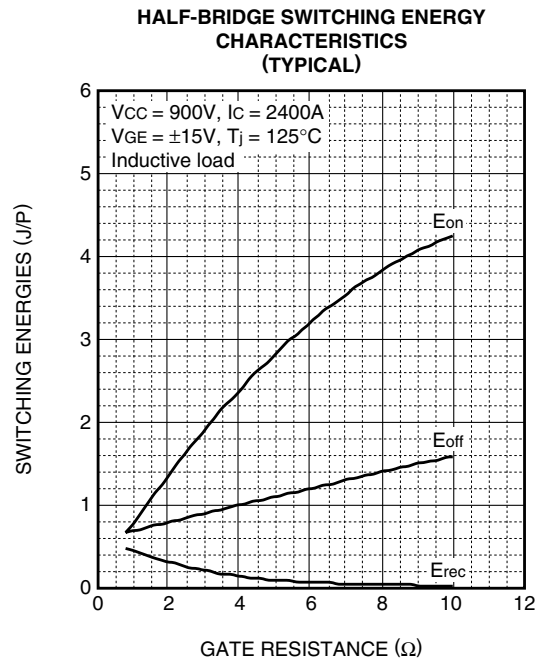
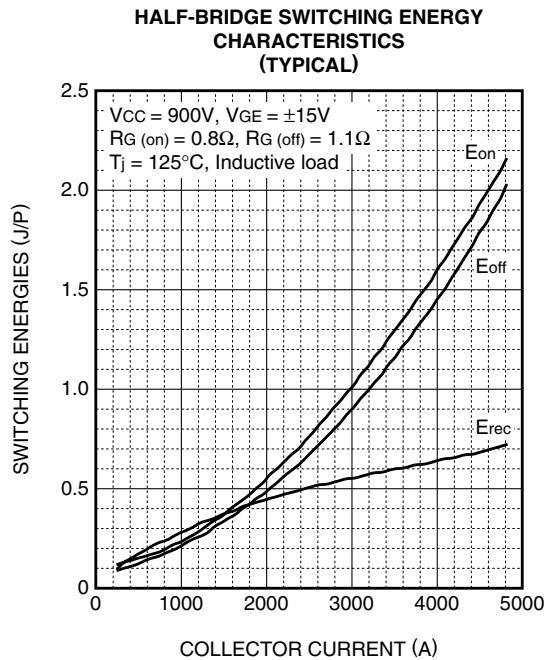
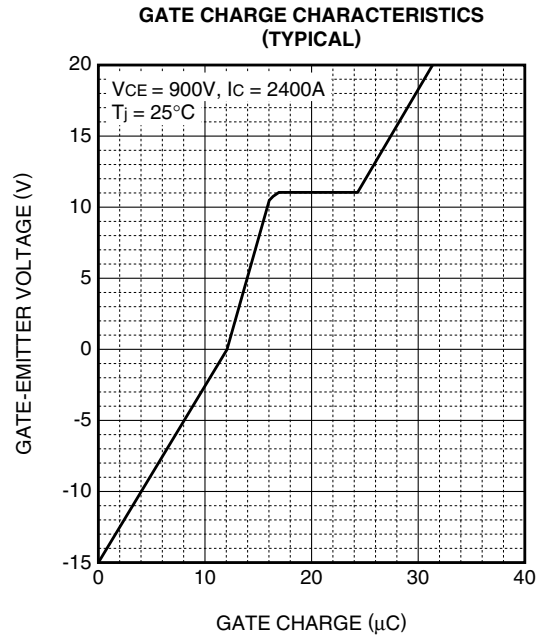
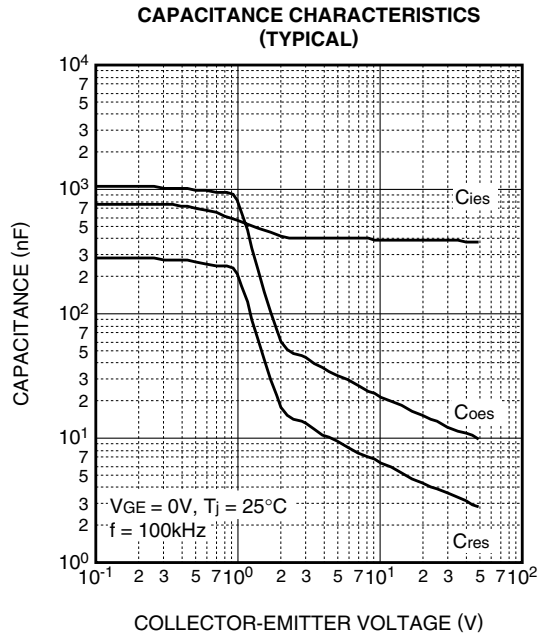
FREE-WHEEL DIODE  
FORWARD CHARACTERISTICS  
(TYPICAL)



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4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

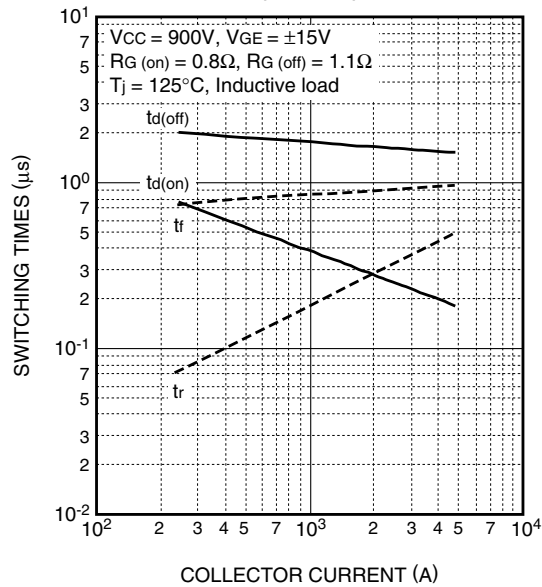


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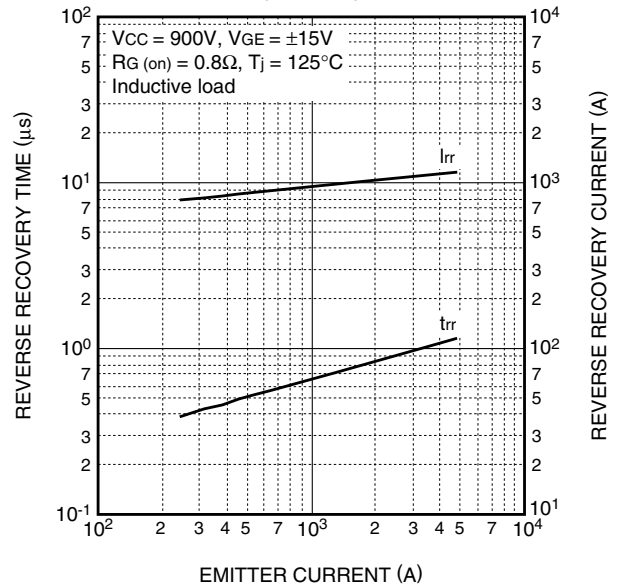
HIGH POWER SWITCHING USE  
INSULATED TYPE

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

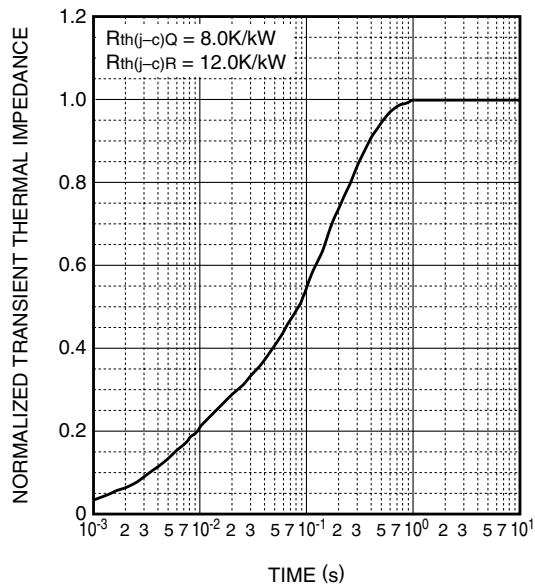
HALF-BRIDGE SWITCHING TIME  
CHARACTERISTICS  
(TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY  
CHARACTERISTICS  
(TYPICAL)



TRANSIENT THERMAL IMPEDANCE  
CHARACTERISTICS



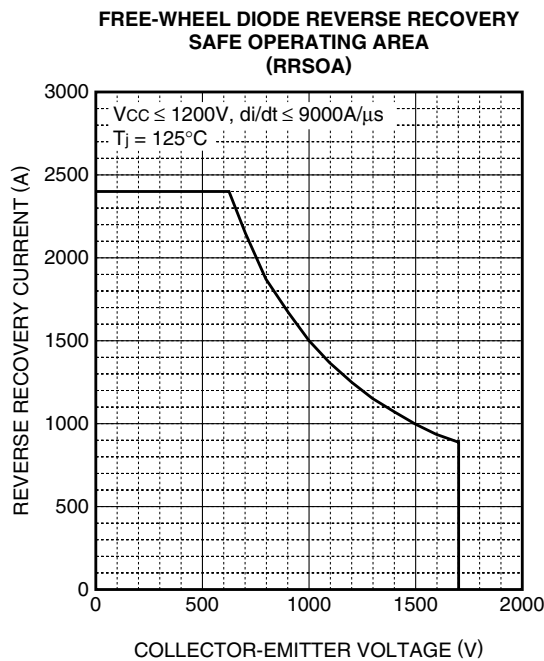
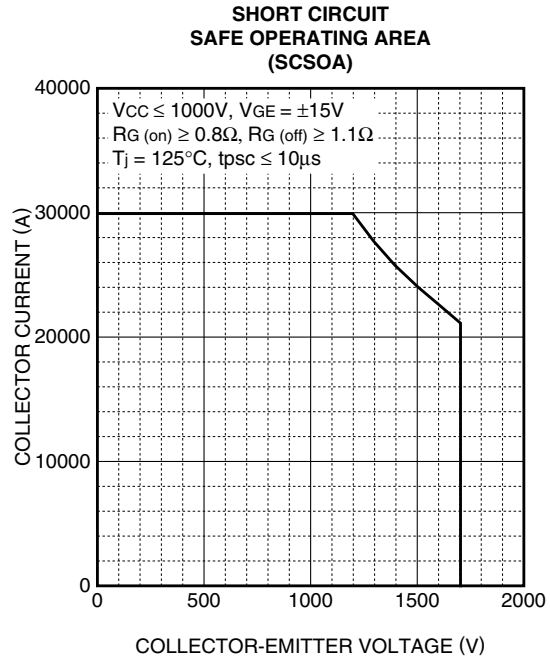
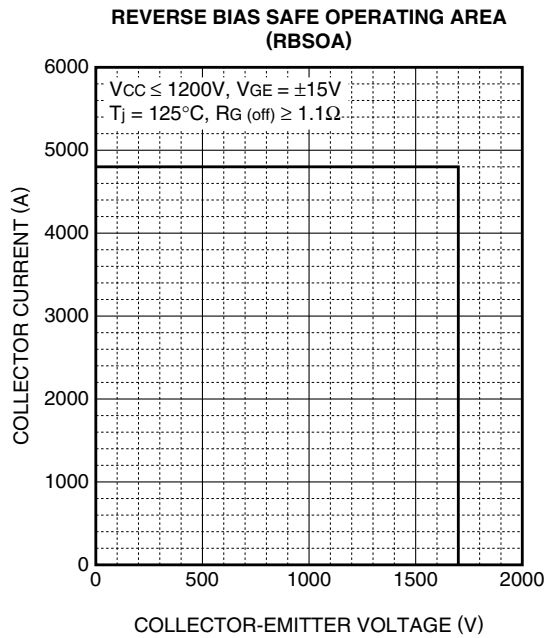
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4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



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